

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A heat dissipation device comprising:
a base; and
a plurality of fins connected to said base and extending out from said base at a non-orthogonal angle to said base, wherein said plurality of fins are substantially parallel.
2. (Original) The heat dissipation device of Claim 1 wherein said non-orthogonal angle is substantially forty-five degrees.
3. (Original) The heat dissipation device of Claim 1 wherein said heat dissipation device is configured to be thermally coupled to an electronic component for dissipating heat generated by said electronic component.
4. (Original) The heat dissipation device of Claim 3 wherein said electronic component is a microprocessor.
5. (Original) The heat dissipation device of Claim 1 wherein said heat dissipation apparatus is comprised of aluminum.
6. (Original) The heat dissipation device of Claim 1 wherein said heat dissipation apparatus is comprised of copper.

7. (Original) The heat dissipation device of Claim 1 further comprising a fan disposed perpendicular to said plurality of fins, said fan for moving air across said plurality of fins.

8. (Currently Amended) An electronic device comprising:
a computer component; and
a tilted fin heat sink thermally coupled to said computer component for dissipating heat generated by said computer component, said tilted fin heat sink comprising a base and a plurality of fins, wherein said plurality of fins extend out from said base of said heat sink at a non-orthogonal angle to said base and wherein said plurality of fins are substantially parallel, said tilted fin heat sink for dissipating heat generated by said computer component.

9. (Original) The electronic device of Claim 8 wherein said non-orthogonal angle is substantially forty-five degrees.

10. (Original) The electronic device of Claim 8 wherein said tilted fin heat sink is comprised of aluminum.

11. (Original) The electronic device of Claim 8 wherein said tilted fin heat sink is comprised of copper.

12. (Original) The electronic device of Claim 8 further comprising a fan disposed perpendicular to said plurality of fins, said fan for moving air across said plurality of fins.

13. (Original) The electronic device of Claim 8 wherein said computer component is a microprocessor.

14. (Currently Amended) A circuit board comprising:
a card connector for connecting to a card such that said card extends out from said card connector at a first non-orthogonal angle to said card connector;
an electronic component; and
a tilted fin heat sink mounted to said electronic component, wherein fins of said heat sink extend out from a base of said heat sink at a second non-orthogonal angle to said base, and wherein said plurality of fins are substantially parallel; and
wherein said card connector and said electronic component are proximately placed such that said card extends out from said card connector and overlaps said fins wherein said fins are at least partially between said circuit board and said card and wherein said card and said fins do not come in physical contact.

15. (Original) The circuit board of Claim 14 wherein said first non-orthogonal angle and said second non-orthogonal angle are substantially equal.

16. (Original) The circuit board of Claim 15 wherein said first non-orthogonal angle and said second non-orthogonal angle are substantially forty-five degrees.

17. (Original) The circuit board of Claim 14 wherein said card and said fins are substantially parallel.

18. (Original) The circuit board of Claim 14 wherein said card is a dual in-line memory module (DIMM).

19. (Original) The circuit board of Claim 14 wherein said electronic component is a microprocessor.

20. (Original) The circuit board of Claim 14 wherein said electronic component is an integrated circuit.